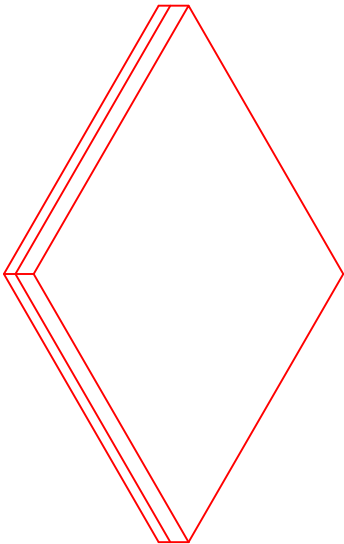




REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0631-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0619-2062: MARKING.

PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 40.

THE MAXIMUM SOLDER BALL MATRIX SIZE IS 8 X 8.

THE BASIC SOLDER BALL GRID PITCH IS 0.50.

ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

3: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL XX ±0.10 XXX ±0.05 XXXX ±0.03 ANGULAR ±1°	PROJECTION		APPROVALS		DATE	ANAM Industrial Co., LTD. Sungdong-Dong, Seoul, Korea	AMCOR Electronics, Inc. Chandler, Arizona, USA	
	DRAWN D. BIGGS		01/20/98					
	CHECKED D. GASTELUM		01/20/98					
MATERIAL N/A	NOTED T. PANCAZAK		01/20/98					
FINISH N/A	RELEASED M. ANTONIO		01/22/98					
DO NOT SCALE DRAWING								

TITLE PACKAGE OUTLINE - CABGA 40, 5.00mm X 5.00mm, 2 LAYER, 0.50mm PITCH, LAMINATE SUBSTRATE, AAP			
SIZE B	N/A		DWG NUMBER 73349
SHEET TWO NUMBER/REV/CUST CODE N/A	SCALE: 8:1		
SHEET 1 OF 3			